

What is claimed is:

1. A method of producing a chip thermistor, said method comprising the steps of:
  - 5 preparing green sheets containing a NTC thermistor ceramic material and an organic binder, said thermistor ceramic material having property of becoming thermistor ceramic by a firing process;
  - applying a resistor paste on one or more of said green sheets, said resistor paste having property of becoming a resistor by a firing process;
  - 10 applying an inner electrode paste on others of said green sheets;
  - forming a layered structure having mutually opposite end surfaces by stacking and compressing together specified numbers of said green sheets, said one or more green sheets and said other green sheets, no PTC thermistor materials being included in said layered structure;
  - 15 subjecting said layered structure to a firing process to form one or more resistors with resistance greater than  $1\Omega$ ; and
  - forming outer electrodes on said outer end surfaces.
2. The method of claim 10 wherein said thermistor material includes oxides of
  - 20 at least one selected from the group consisting of Mn, Ni, Co, Cu, Al and Fe, and said resistor paste includes at least one selected from the group consisting of PdO, Pd,  $\text{Lu}_2\text{O}_3$ , SiC and mixtures thereof.